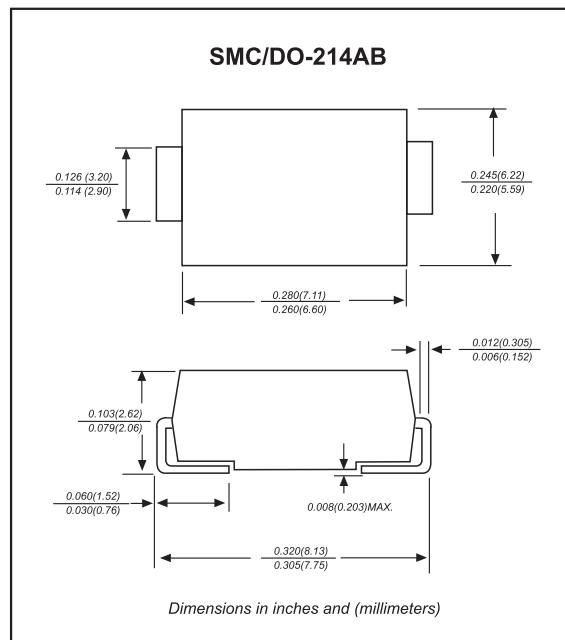


ES3A-C THRU ES3J-C**Formosa MS****3.0A Surface Mount Super
Fast Rectifiers-50-600V****Features**

- ◆ The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- ◆ For surface mounted applications
- ◆ Super fast switching for high efficiency
- ◆ Low reverse leakage
- ◆ Built-in strain relief, ideal for automated placement
- ◆ High forward surge current capability
- ◆ High temperature soldering guaranteed: 250°C/10 seconds at terminals
- ◆ Glass passivated chip junction
- ◆ Compliant to RoHS Directive 2011/65/EU
- ◆ Suffix "-H" indicates Halogen-free part, ex. ES3J-C-H

Mechanical data

- ◆ **Case:** JEDEC DO-214AB molded plastic body
- ◆ **Terminals:** Solder plated, solderable per MIL-STD-750, Method 2026
- ◆ **Polarity:** Color band denotes cathode end
- ◆ **Mounting Position:** Any
- ◆ **Weight:** 0.007 ounce, 0.25 grams

Package outline**Maximum ratings and Electrical Characteristics (AT $T_A=25^\circ\text{C}$ unless otherwise noted)**

PARAMETER	CONDITIONS			Symbol	MIN.	TYP.	MAX.	UNIT
Forward rectified current	See Fig.2			I_o			3.0	A
Forward surge current	8.3ms single half sine-wave (JEDEC method)			I_{FSM}			80	A
Reverse current	$V_R = V_{RRM} T_A = 25^\circ\text{C}$			I_R			5.0	μA
	$V_R = V_{RRM} T_A = 100^\circ\text{C}$						50	
Thermal resistance	Junction to ambient NOTE 1			$R_{\theta JA}$		47		$^\circ\text{C}/\text{W}$
Diode junction capacitance	$f=1\text{MHz}$ and applied 4V DC reverse voltage			C_J		45		pF
Storage temperature				T_{STG}	-65		+150	$^\circ\text{C}$

SYMBOLS	V_{RRM} *1 (V)	V_{RMS} *2 (V)	V_R *3 (V)	V_F *4 (V)	t_{rr} *5 (ns)	Operating temperature T_J , ($^\circ\text{C}$)
ES3A-C	50	35	50			
ES3B-C	100	70	100			
ES3C-C	150	105	150			
ES3D-C	200	140	200			
ES3E-C	300	210	300			
ES3G-C	400	280	400			
ES3J-C	600	420	600	1.70		

*1 Repetitive peak reverse voltage

*2 RMS voltage

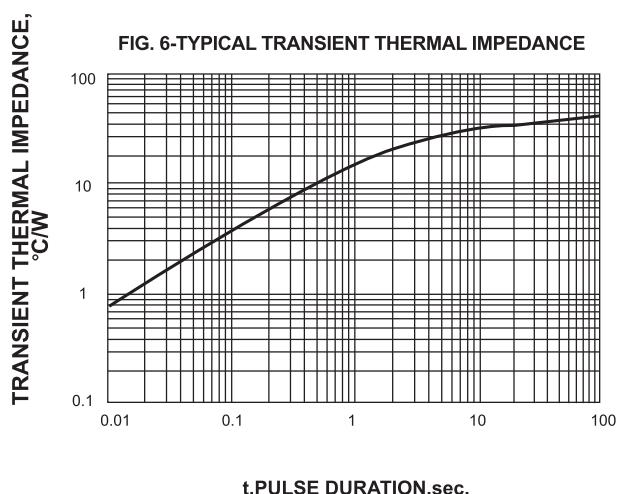
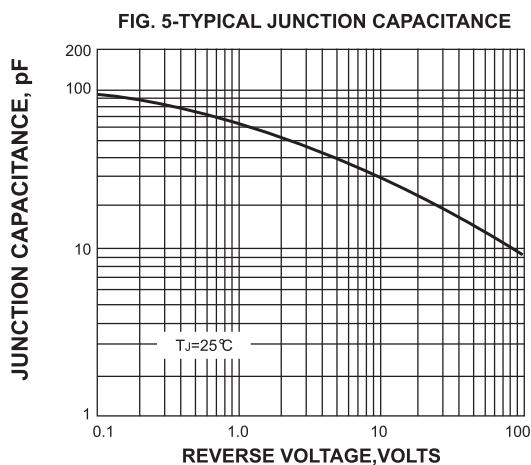
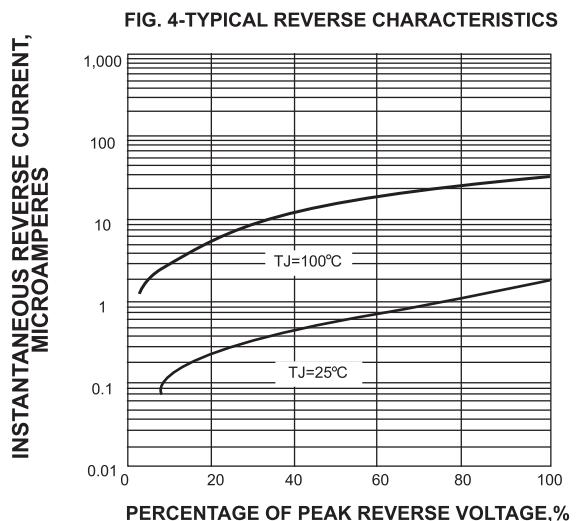
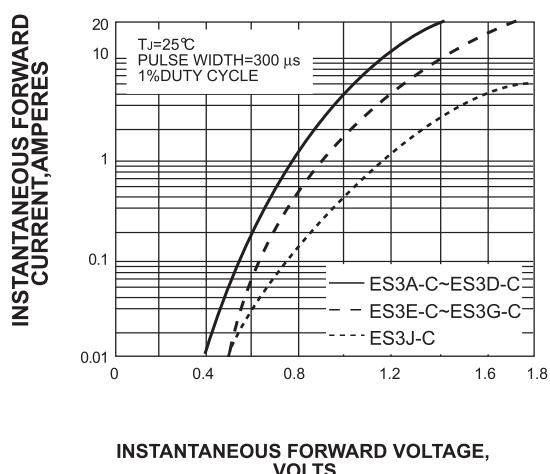
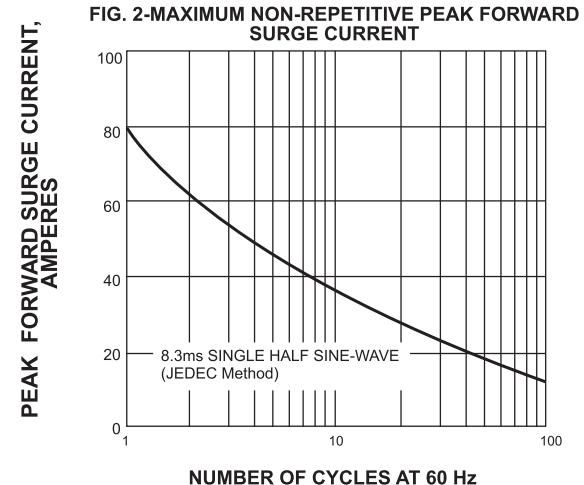
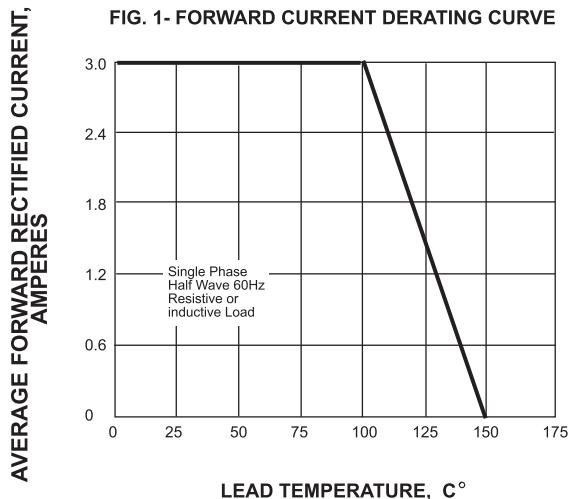
*3 Continuous reverse voltage

*4 Maximum forward voltage@ $I_F=3.0\text{A}$

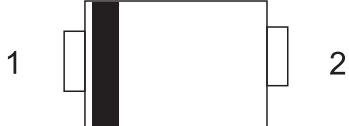
*5 Maximum Reverse recovery time, note 2

Note: 1.P.C.B. mounted with 0.2x0.2"(5.0x5.0mm) copper pad areas

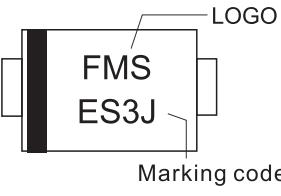
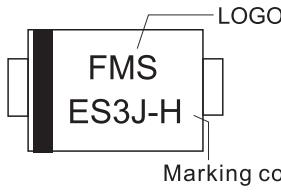
2. Reverse recovery time test condition, $I_F=0.5\text{A}$, $I_R=1.0\text{A}$, $I_{RR}=0.25\text{A}$ 

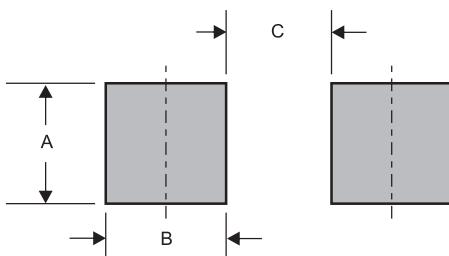
ES3A-C THRU ES3J-C**Formosa MS****Rating and characteristic curves**

ES3A-C THRU ES3J-C**Formosa MS****Pinning information**

Pin	Simplified outline	Symbol
Pin1 cathode Pin2 anode		

Marking

Type number	Marking code	Example	
ES3A-C	ES3A	For Halogen Device	For Halogen-free Device
ES3B-C	ES3B		
ES3C-C	ES3C		
ES3D-C	ES3D		
ES3E-C	ES3E		
ES3G-C	ES3G		
ES3J-C	ES3J		

Suggested solder pad layout

Dimensions in inches and (millimeters)

PACKAGE	A	B	C
SMC	0.132 (3.30)	0.100 (2.50)	0.176(4.40)